

STGB19NC60S STGP19NC60S

20 A, 600 V fast IGBT

Features

- Very low on-voltage drop (V_{CE(sat)})
- Minimum power losses at 5 kHz in hard switching
- Optimized performance for medium operating frequencies.

Application

Medium frequency motor drives

Description

This IGBT utilizes the advanced PowerMESH[™] process resulting in an excellent trade-off between switching performance and low on-state behavior.

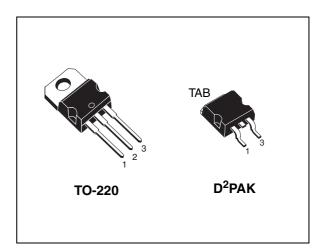


Figure 1. Internal schematic diagram

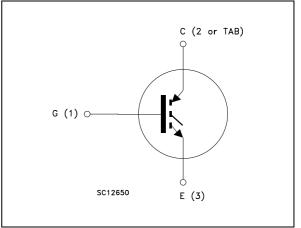


Table 1.	Device	summary
	Device	Summary

Order codes	Marking	Package	Packaging
STGB19NC60ST4	GB19NC60S	D ² PAK	Tape and reel
STGP19NC60S	GP19NC60S	TO-220	Tube

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1 Electrical ratings

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600	V
I _C ⁽¹⁾	Collector current (continuous) at $T_C = 25^{\circ}C$	50	А
I _C ⁽¹⁾	Collector current (continuous) at T _C = 100°C	20	А
I _{CP} ⁽²⁾	Pulsed collector current	80	А
I _{CL} ⁽³⁾	Turn-off latching current	80	А
V _{GE}	Gate-emitter voltage	±20	V
P _{TOT}	Total dissipation at $T_{C} = 25^{\circ}C$	125	W
Тj	Operating junction temperature	– 55 to 150	°C

1. Calculated according to the iterative formula

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_{C}(T_{C}))}$$

2. Pulse width limited by maximum junction temperature and turn-off within RBSOA

3. Vclamp = 80% of V_{CES}, T_j =150 °C, R_G=10 Ω , V_{GE}=15 V

Table 3.Thermal data

Symbol	Symbol Parameter		Unit
R _{thj-c}	Thermal resistance junction-case	1	°C/W
R _{thj -a}	Thermal resistance junction-ambient	62.5	°C/W



2 Electrical characteristics

(T_j = 25° C unless otherwise specified)

Table 4.	Static
	Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 1mA	600			V
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15V, I _C = 12A V _{GE} = 15V, I _C =12A,T _j =125°C		1.55 1.35	1.9	V V
V _{GE(th)}	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 250 \ \mu A$	3.75		5.75	V
I _{CES}	Collector cut-off current (V _{GE} = 0)	V _{CE} = 600 V V _{CE} = 600 V, T _j =125°C			150 1	μA mA
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V_{GE} = ±20V, V_{CE} = 0			±100	nA
9 _{fs}	Forward transconductance	V _{CE} = 15V _, I _C = 12A		10		S

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	V _{CE} = 25V, f = 1MHz, V _{GE} = 0	-	1190 135 28.5	-	pF pF pF
Q _g Q _{ge} Q _{gc}	Total gate charge Gate-emitter charge Gate-collector charge	V_{CE} = 480V, I _C = 12A, V_{GE} = 15V, <i>Figure 18</i>	-	54.5 8.7 25.8	-	nC nC nC



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt)on	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 480V, I _C = 12A R _G = 10 Ω , V _{GE} = 15V, <i>Figure 19</i>	-	17.5 6.2 1870	-	ns ns A/µs
t _{d(on)} t _r (di/dt)on	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ $T_j = 125^{\circ}C$ <i>Figure 19</i>	-	17 6.5 1700	-	ns ns A/µs
t _{r(Voff)} t _{d(Voff)} t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} = 480V, I _C = 12A R _G = 10 Ω , V _{GE} = 15V, <i>Figure 19</i>	-	90 175 215	-	ns ns ns
$t_{r(Voff)}$ $t_{d(Voff)}$ t_{f}	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ $T_j = 125^{\circ}C$ <i>Figure 19</i>	-	155 245 290	-	ns ns ns

 Table 6.
 Switching on/off (inductive load)

 Table 7.
 Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{on} E _{off} ⁽¹⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480$ V, $I_C = 12$ A R _G = 10 Ω , V_{GE} = 15V, <i>Figure 17</i>	-	135 815 995	-	μJ μJ μJ
E _{on} E _{off} ⁽¹⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ $T_j = 125^{\circ}C$ <i>Figure 17</i>	-	200 1175 1375	-	μJ μJ μJ

1. Turn-off losses include also the tail of the collector current



2.1 Electrical characteristics (curves)

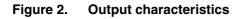
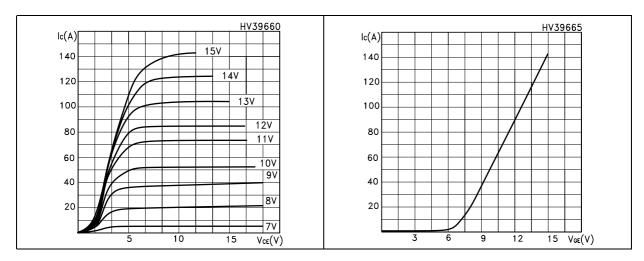


Figure 3. Transfer characteristics



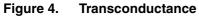


Figure 5. Collector-emitter on voltage vs temperature

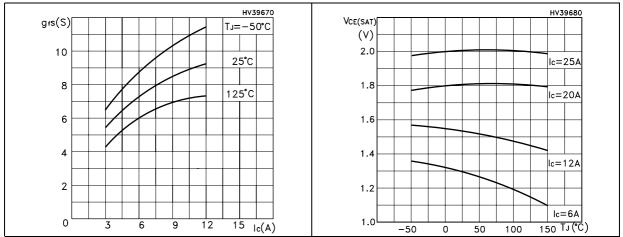


Figure 6. Gate charge vs gate-source voltage Figure 7. Capacitance variations

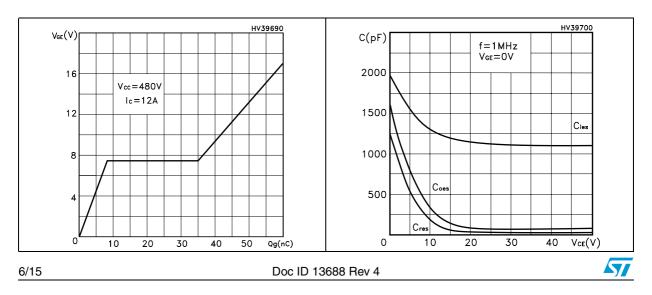
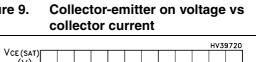


Figure 8. Normalized gate threshold voltage Figure 9. vs temperature



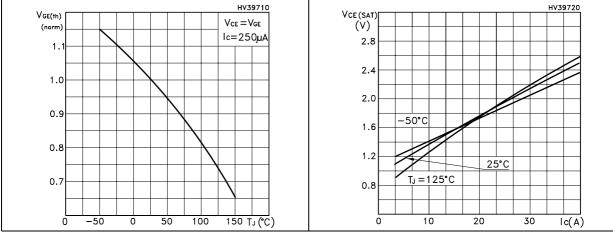


Figure 10. Normalized breakdown voltage vs Figure 11. Switching losses vs temperature temperature

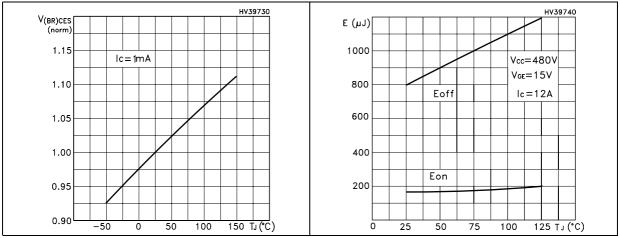


Figure 12. Switching losses vs gate resistance Figure 13. Switching losses vs collector current

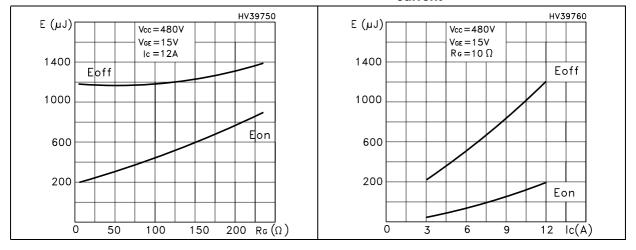




Figure 14. Turn-off SOA

Figure 15. Thermal impedance

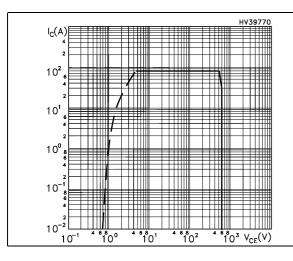
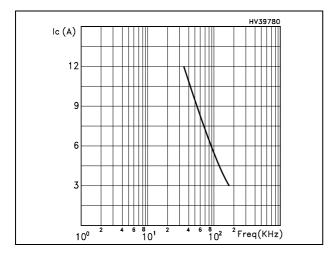
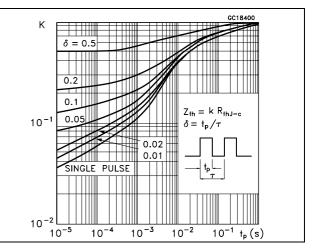


Figure 16. I_C vs. frequency







2.2 Frequency applications

For a fast IGBT suitable for high frequency applications, the typical collector current vs. maximum operating frequency curve is reported. That frequency is defined as follows:

 $f_{MAX} = (P_D - P_C) / (E_{ON} + E_{OFF})$

• The maximum power dissipation is limited by maximum junction to case thermal resistance:

Equation 1

 $P_D = \Delta T / R_{THJ-C}$

considering $\Delta T = T_J - T_C = 125 \text{ °C} - 75 \text{ °C} = 50 \text{ °C}$

• The conduction losses are:

Equation 2

 $\mathsf{P}_{\mathsf{C}} = \mathsf{I}_{\mathsf{C}} * \mathsf{V}_{\mathsf{CE}(\mathsf{SAT})} * \delta$

with 50% of duty cycle, $V_{\mbox{CESAT}}$ typical value @125°C.

• Power dissipation during ON & OFF commutations is due to the switching frequency:

Equation 3

 $P_{SW} = (E_{ON} + E_{OFF}) * freq.$

Typical values @ 125°C for switching losses are used (test conditions: $V_{CE} = 480V$, $V_{GE}=15V$, $R_G = 10$ Ohm). Furthermore, diode recovery energy is included in the E_{ON} (see *Note 1*), while the tail of the collector current is included in the E_{OFF} measurements.



3 Test circuits

Figure 17. Test circuit for inductive load

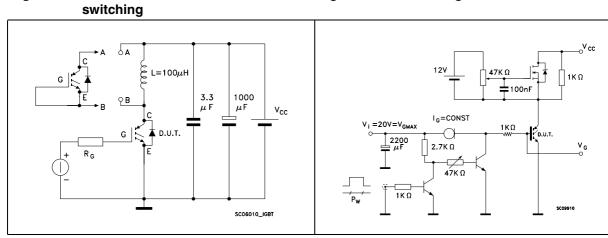


Figure 19. Switching waveform

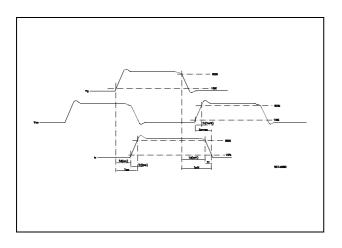


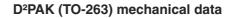
Figure 18. Gate charge test circuit

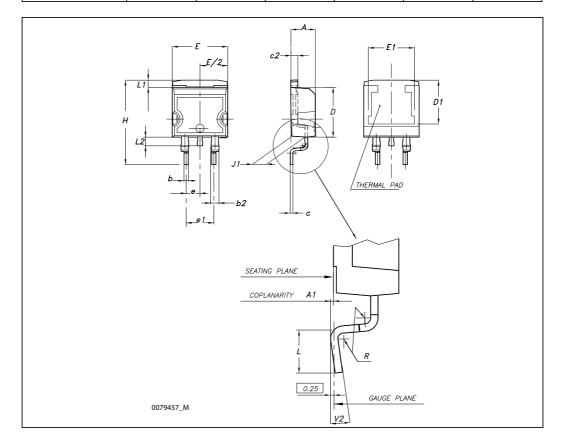
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



Dim		mm			inch	
DIM	Min	Тур	Мах	Min	Тур	Max
А	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.027		0.037
b2	1.14		1.70	0.045		0.067
С	0.45		0.60	0.017		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50			0.295		
E	10		10.40	0.394		0.409
E1	8.50			0.334		
е		2.54			0.1	
e1	4.88		5.28	0.192		0.208
Н	15		15.85	0.590		0.624
J1	2.49		2.69	0.099		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.05		0.055
L2	1.30		1.75	0.051		0.069
R		0.4			0.016	
V2	0°	İ	8°	0°		8°



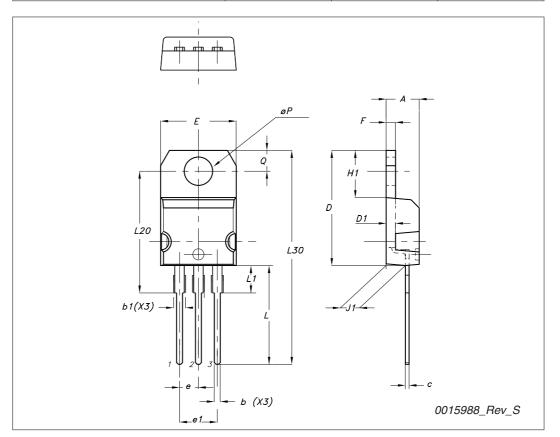


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Dim	mm		
	Min	Тур	Мах
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
С	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95





5 Revision history

Table 8.	Document revision history
	Document revision mistory

Date	Revision	Changes
02-Jul-2007	1	First release
13-Aug-2007	2	From target to preliminary version
18-Sep-2007	3	Added new section: Electrical characteristics (curves)
18-Aug-2009	4	Inserted D ² PAK package



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